ASIC stuffing, Module assembly, and QA's in Japan

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Series production summary as of Mid. February, 2003

1. Deliveries

- Sensors (to assembly site)	2356
- Baseboards (to KEK)	519
- ASICs (to KEK, including in undiced wafers)	9181

2. Assemblies

- ASIC stuffed hybrids (to KEK)	450
- ASIC-hybrids (to assembly site)	307
- Modules (to KEK)	273